## Telescope to Test CMS Pixel Upgrade Detectors

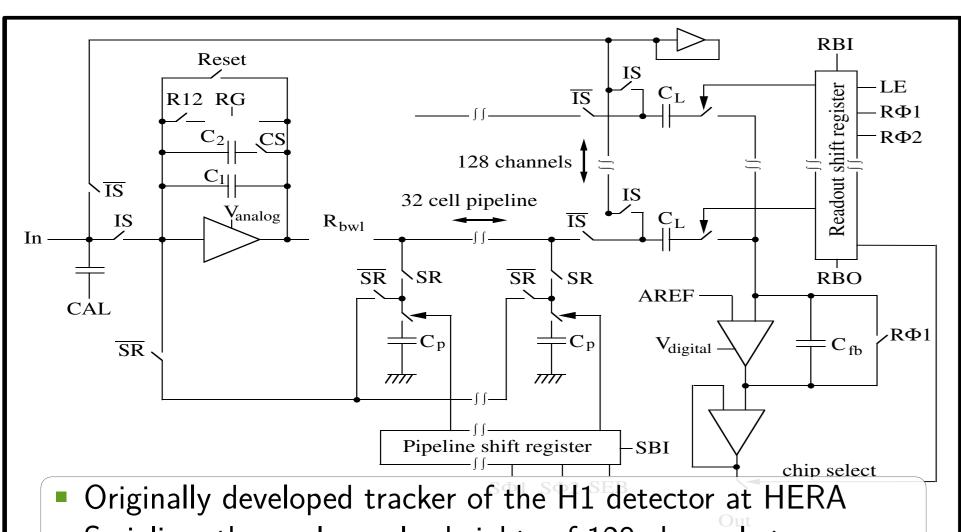
Caleb Fangmeier on behalf of the CMS Collaboration



The innermost layer of the CMS Detector at the LHC is the silicon pixel tracker. The current version of the detector has performed well and been critical to the physics program of CMS. However, as the LHC produces higher instantaneous luminosities and higher center-of-mass energies, the detector must be upgraded to accommodate. The Phase-II Upgrade of CMS will replace the entire silicon tracking system. As part of this upgrade, a new section of the pixel tracker will be added in the so-called "very-forward" (TODO:  $\eta$  range)region of the detector. This new section of the detector will have different pixel geometries than the current detector, and these new geometries must be accurately characterized. Therefore, a telescope is being developed for the express purpose of characterizing these sensors so the pixel geometry can be optimized before settling on a final design to be placed in CMS. The telescope operates by using eight layers of silicon-strip sensors, with the device-under-test placed with four on each side. A charged-particle beam is directed so it passes through both the strip sensors and the device-under-test. Measurements from the telescope are taken to reconstruct individual particle tracks.

## Hardware

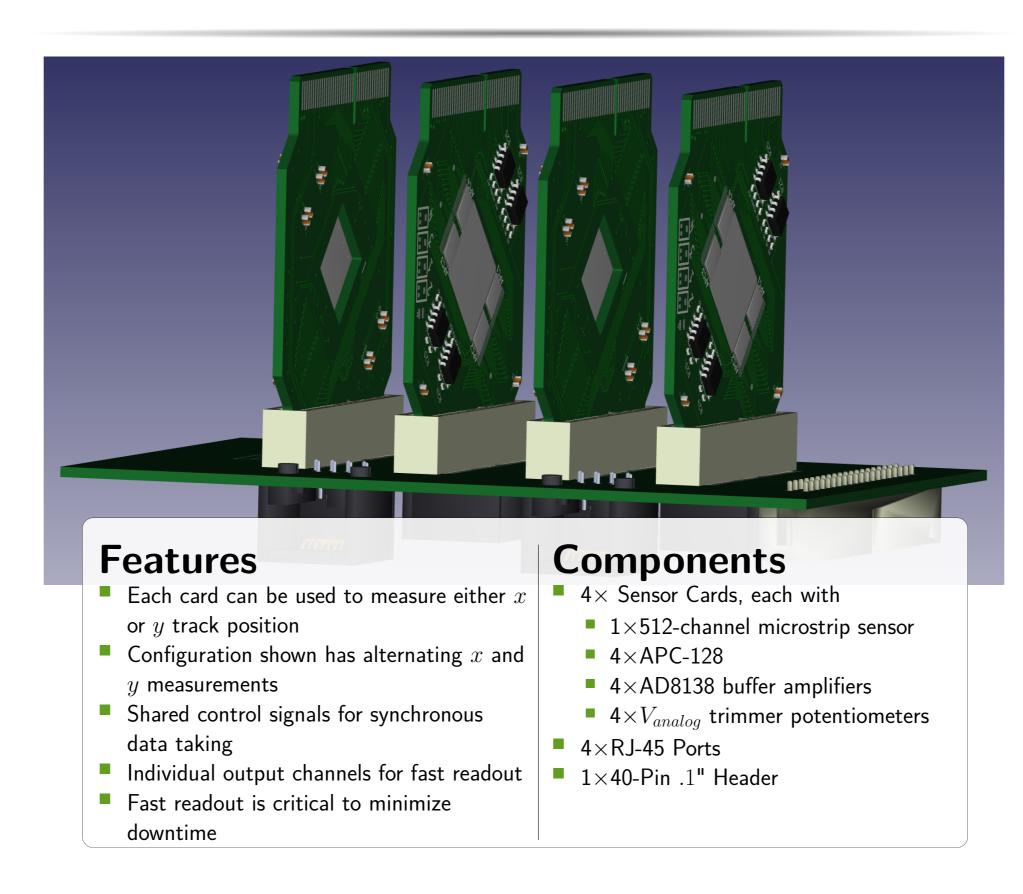
## Analog Pipeline Chip (APC-128)



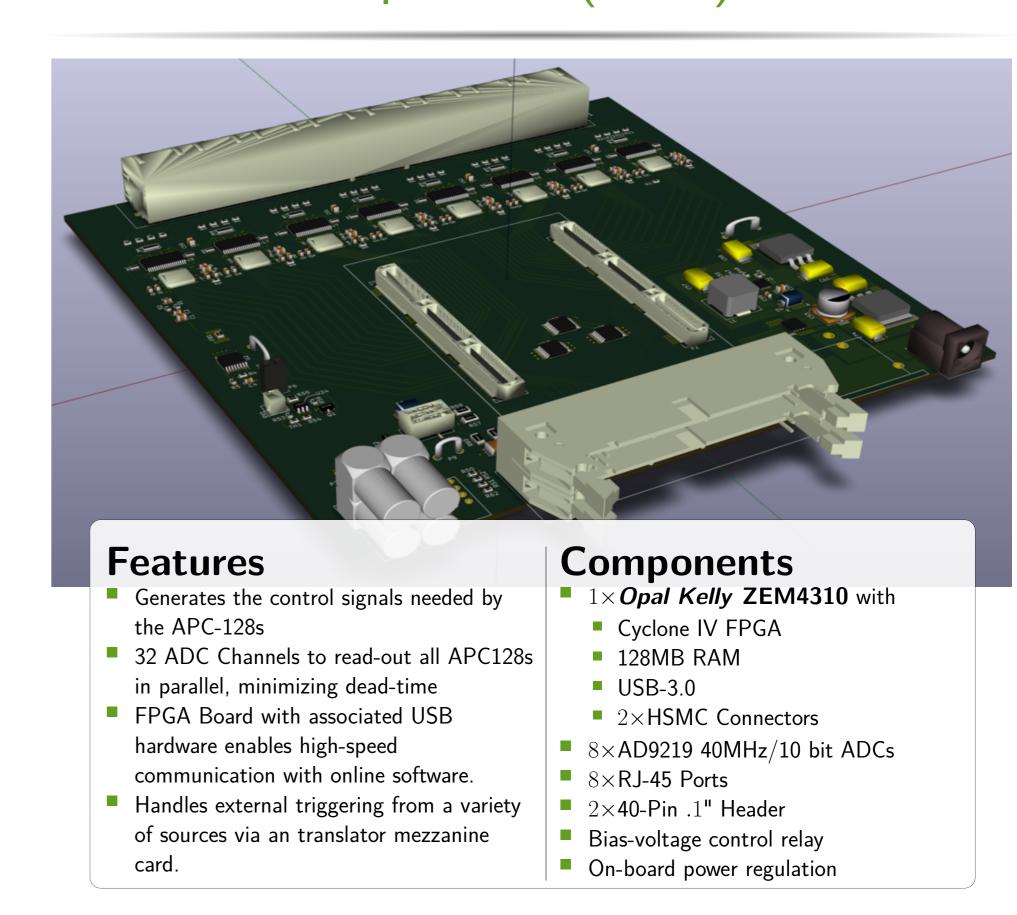
- Serializes the analog pulse-heights of 128 channels to
- dramatically reduce the number of required I/O lines

  Capable of campling waveform data from of a strip cons
- Capable of sampling waveform data from of a strip sensor at upwards of 20MHz
- Features a very good signal-to-noise ratio of 40.
- Low noise combined with inter-strip charge-sharing give each layer of the detector a measurement precision of  $\approx 1 \mu \mathrm{m}$

## Sensor Board



## Data Acquisition (DAQ) Board



## Readout Scheme

## In-Beam Electronics STRIP SENSOR OUTPUT APC-128 OUTPUT CHARGE SHARED AMONG 3 STRIPS TIME TIME STRIP \*

- The sensor is essentially a silicon NP-Junction operated in "reverse-bias" mode where all free charge carriers are evacuated
- An energetic charged particle passing through the silicon deposits energy to create free electron-hole pairs which are then separated by the electric field produced by the biasing voltage
- The electrons create a current spike that the readout chip, the APC-128, samples and stores
- Upon receiving a trigger, the APC-128 serializes the analog pulse-height sample from each of the 128 channels

### **DAQ Board** DIGITIZED PULSE-HEIGHT VALUES HIT DETECTION HIT\_START 18/16/14/11/19/20/16/16/17/18/16/17/23/17 SENSOR: 6 17/18/17/15/16/21/50/115/59/24/18/17/14/15 STRIP: 7 PULSE HEIGHT: 50 17/14/15/17/17/14/16/22/12/14/13/26/20 STRIP: 8 PULSE HEIGHT: 115 18 19 17 17 27 23 55 112 54 15 18 16 18 19 STRIP: 9 PULSE\_HEIGHT: 59 HIT END

- The analog pulse-heights from the 32 APC-128 in the telescope are digitized by 8 high-speed 4-channel ADCs located on the DAQ board
- The digitized values passed to an FPGA board where they are processed into individual sensor hits
- Digitized values smaller than the noise-suppression threshold are dropped
- The sensor hit data is passed across a USB-3 connection to a PC.
- Its job finished, the DAQ Board becomes idle and waits for the next trigger.

# EVENT CONSTRUCTION EVENT\_START TIMESTAMP: 123453234.12345 SENSOR\_1\_POSITION: 1.254 mm SENSOR\_2\_POSITION: 6.231 mm ... SENSOR\_8\_POSITION: 1.25 mm EVENT\_END

- Online softare organizes the hits into events and stores them to disk
- Since the detector layers can shift in space significantly during operation, alignment must first be done to accurately measure the geometry of the detector.
- After alignment, the various layer hits can be combined to construct extremely precise tracks.
- The tracks can then be compared for consistency with the data collected in parallel from the device-under-test, and, using the telescope as the ground truth, establish performance characteristics.

### Progress

- ✓System design and parts selection
- ✓ Circuit design and PCB Layout
- ☐ Assembly and offline testing (in progress)
- □FPGA Firmware development and testing
- □Online/Offline software development
- □Commissioning runs with UNL Diocles electron beam

## References

- PCB Design Files https://github.com/cfangmeier/VFPIX-
- https://github.com/cfangmeier/VFPIXtelescope-PCB
- reference 3reference 4
- CMS Phase-II Upgrade
  - Acknowledgments

Beat Meier & Tilman Rohe of **The Paul Scherrer Institute**Frank Meier of **Heidelberg University**Aaron Dominguez & Rachel Bartek of **Catholic University of America** 

PUT SOMETHING HERE!!!!

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